

# Far-Forward Calorimetry with the SiD and FCAL collaborations

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Bruce Schumm  
UC Santa Cruz Institute  
for Particle Physics



# FCAL Collaboration

SiD efforts on ILC far-forward calorimetry (LumiCal, BeamCal) are done within the context of the broad FCAL collaboration

~70 physicists; ~20 institutions

Current SiD contributions are solely to BeamCal:

- \* Front-end electronics design (BEAN chip)
- \* Sensor technology studies (SLAC T506 radiation damage studies)
- \* Beamcal reconstruction and physics studies



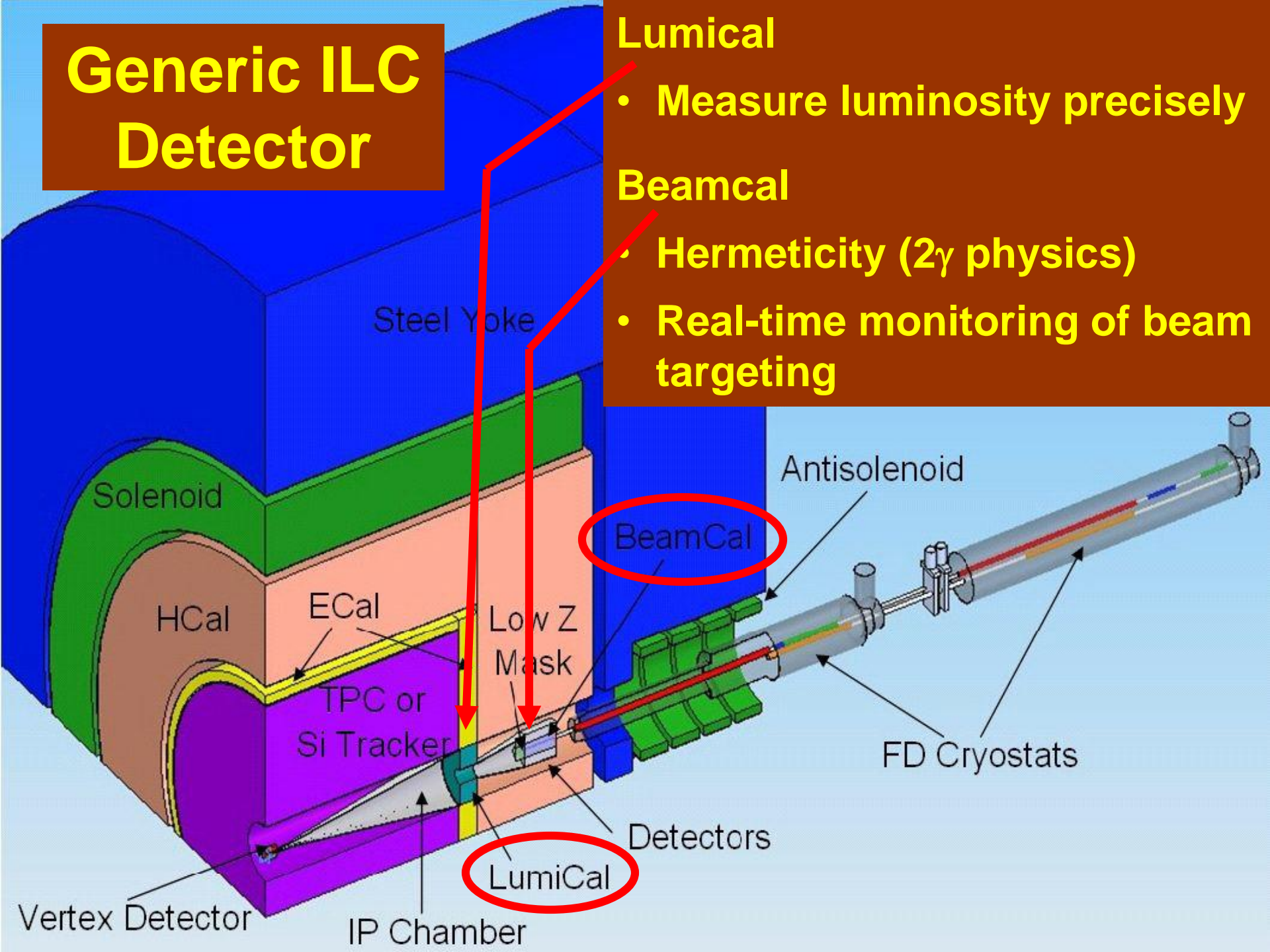
# Generic ILC Detector

## LumiCal

- Measure luminosity precisely

## BeamCal

- Hermeticity ( $2\gamma$  physics)
- Real-time monitoring of beam targeting



Steel Yoke

Solenoid

HCal

ECal

TPC or  
Si Tracker

Low Z  
Mask

BeamCal

Antisolensoid

FD Cryostats

Detectors

LumiCal

Vertex Detector

IP Chamber

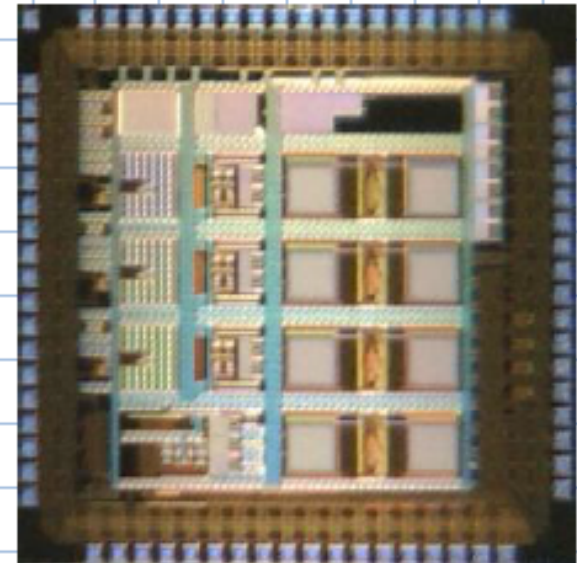
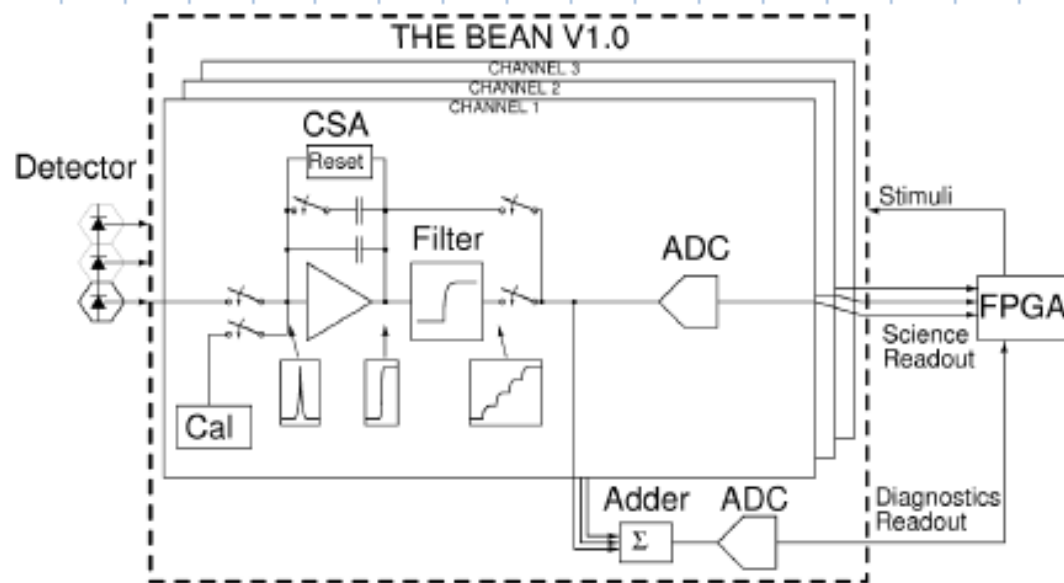
# **BeamCal Front-End Electronics (BEAN Chip)**

**Lead: Prof. Angel Abusleme  
Pontificia Universidad Catolica  
de Chile**

# Basic BeamCal Readout Design Considerations

- 100% occupancy: beam-beam backgrounds will illuminate most channels on every beam crossing
- Large dynamic range (up to 40pC)
- MIP calibration
- Real-time beam condition monitoring (real-time addition of 32 readout channels)

# The Bean V1.0: 3-channel readout chain in 180nm (2010)



- 72 pads, 2.4mm x 2.4mm (including pads)
- 7306 nodes, 35789 circuit elements
- 360 $\mu$ m channel pitch (including power bus)
- 3 charge amplifiers, 4 x 10-bit, fully diff. SAR ADCs, 1 SC adder, 3 SC filters, etc.

# BEAN Chip Ongoing Work

- Refined filtering techniques to maximize S/N
- Explore non-linear ADC
- Testing and characterization
- Digital back-end (must store entire train)
- Contribution to systems development (testbeam prototype)

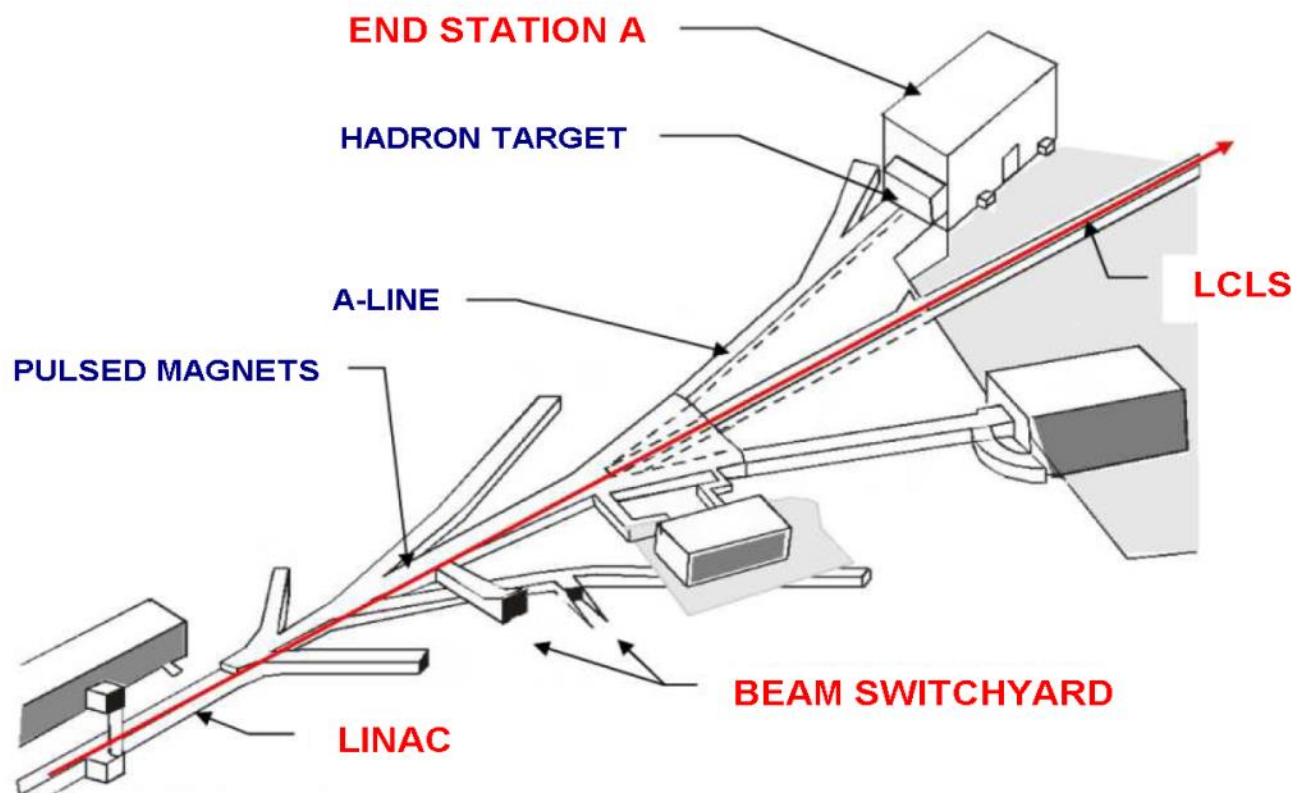
# **SLAC T506 Electromagnetic Radiation Damage Study**

## **Update and Plans**



# LCLS and ESA

Use pulsed magnets in the beam switchyard to send beam in ESA.



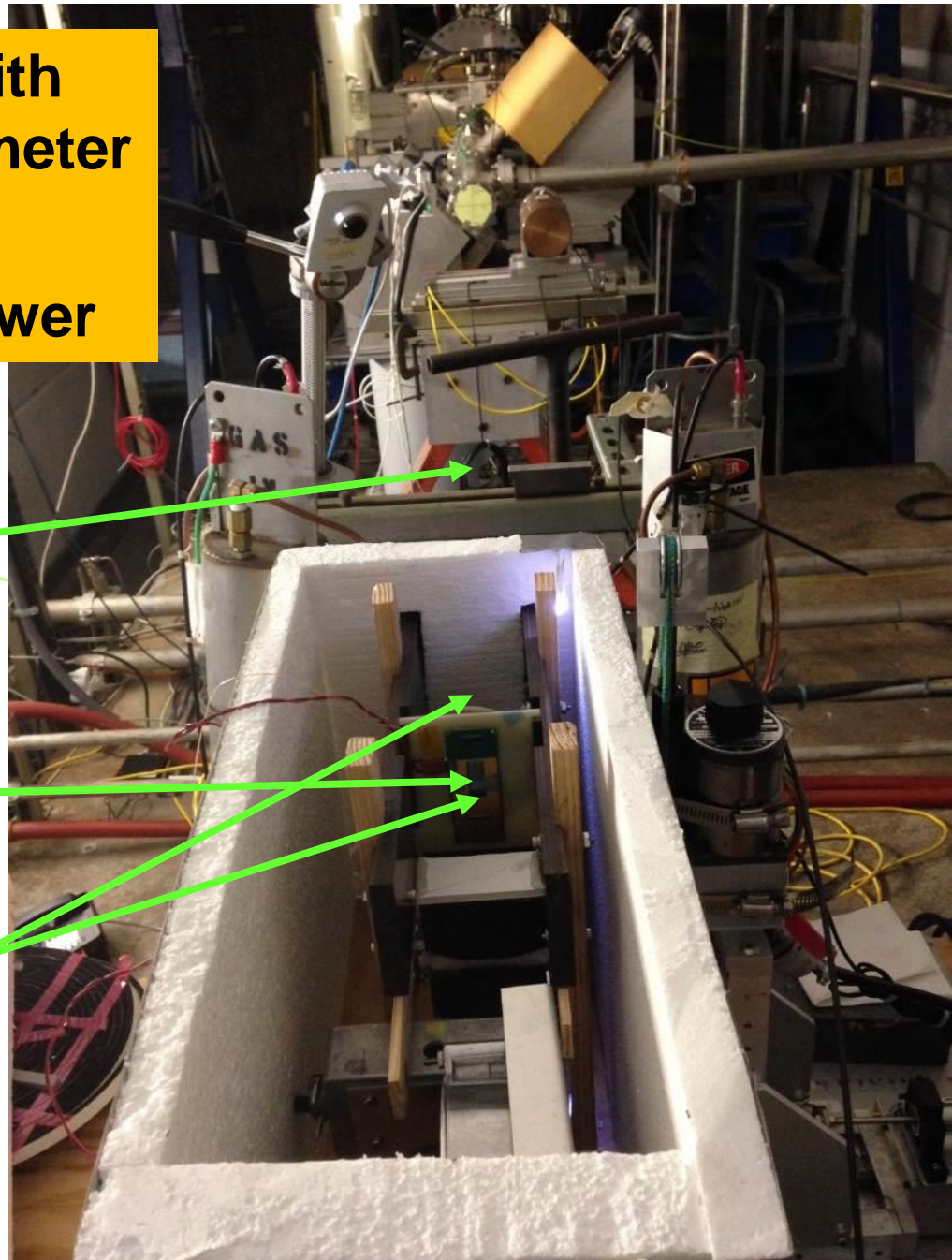
**Surround sensor with  
Tungsten as in calorimeter**

**→ Realistic  
electromagnetic shower**

2  $X_0$  pre-radiator;  
introduces a little  
divergence in  
shower

Sensor sample

Not shown: 4  $X_0$   
and 8  $X_0$  radiators  
just before and after  
sensor



# Dose Rates (Including 1 cm<sup>2</sup> Rastering)

Mean fluence per  
incident e<sup>-</sup>



Electron Energy (GeV)	Shower Conversion Factor $\alpha$	Dose per nC Delivered Charge (kRad)
2	2.1	0.34
4	9.4	1.50
6	16.5	2.64
8	23.5	3.76
10	30.2	4.83
12	36.8	5.89

**Confirmed  
with RADFET  
to within 10%**

**Maximum dose rate (10.6 GeV; 10 Hz; 150 pC per pulse):**

**28 Mrad per hour**

# T506 Si Doses

“P” = p-type

“N” = n-type

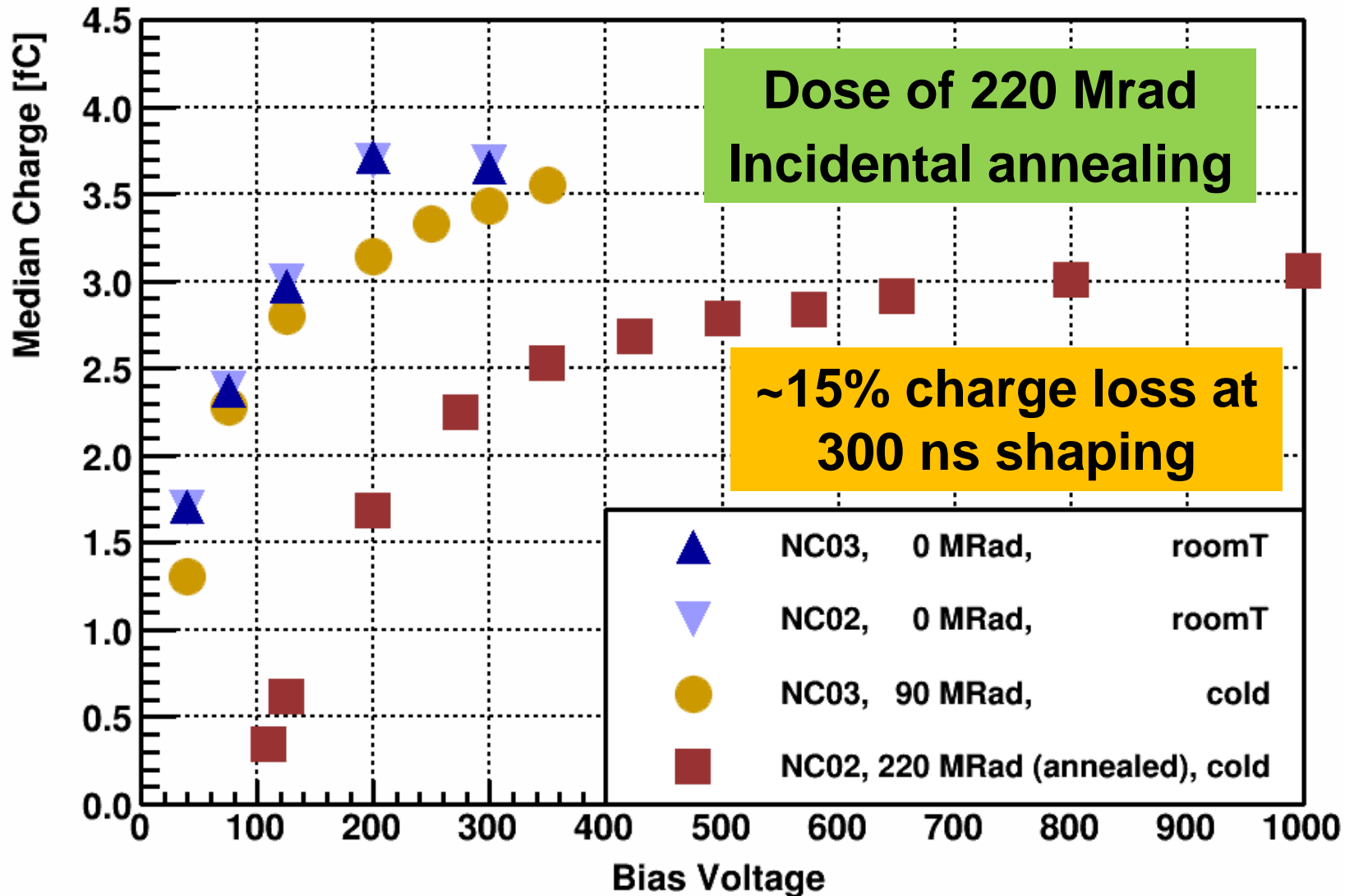
“F” = float zone

“C” = Czochralski

Sensor	$V_{FD}$	Irradiation Temp. (C)	Beam Energy (GeV)	Delivered Charge ( $\mu\text{C}$ )	Dose (MRad)
PF05	190	0	5.88	2.00	5.13
PF14	190	0	3.48	16.4	19.7
PC10	660	0	5.88	1.99	5.12
PC08	700	0	(5.88, 4.11, 4.18)	(3.82,3.33,3.29)	20.3
NF01	90	0	4.18	2.30	3.68
NF02	90	0	4.02	12.6	19.0
NF07	100	5	8.20	23.6	91.4
NC01	220	0	5.88	2.00	5.13
NC10	220	0	3.48	15.1	18.0
NC03	220	5	4.01	59.9	90.2
NC02	220	5*	(10.60,8.20)	(32.3,13.8)	220

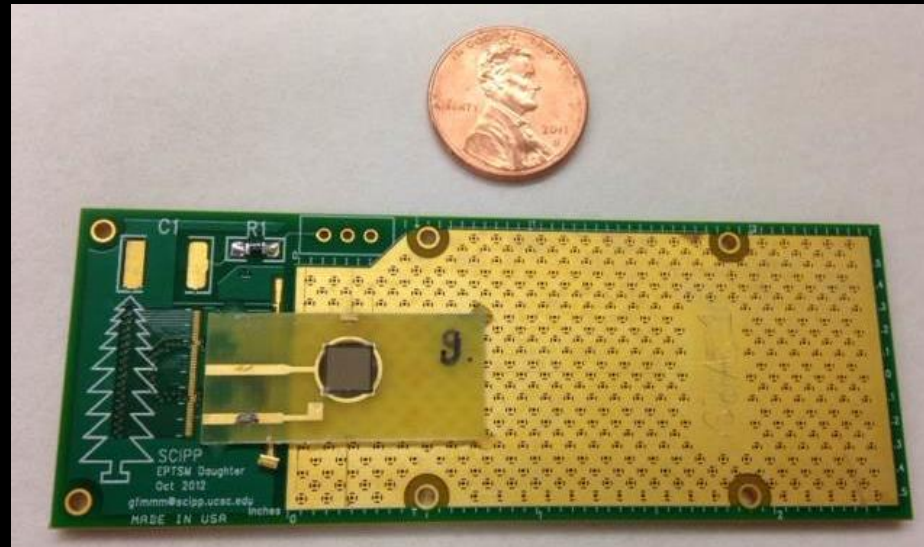
# Results: NC sensors

Median Charge vs Bias Voltage, N-type Magnetic Czochoalski sensors



# T506 GaAs Doses

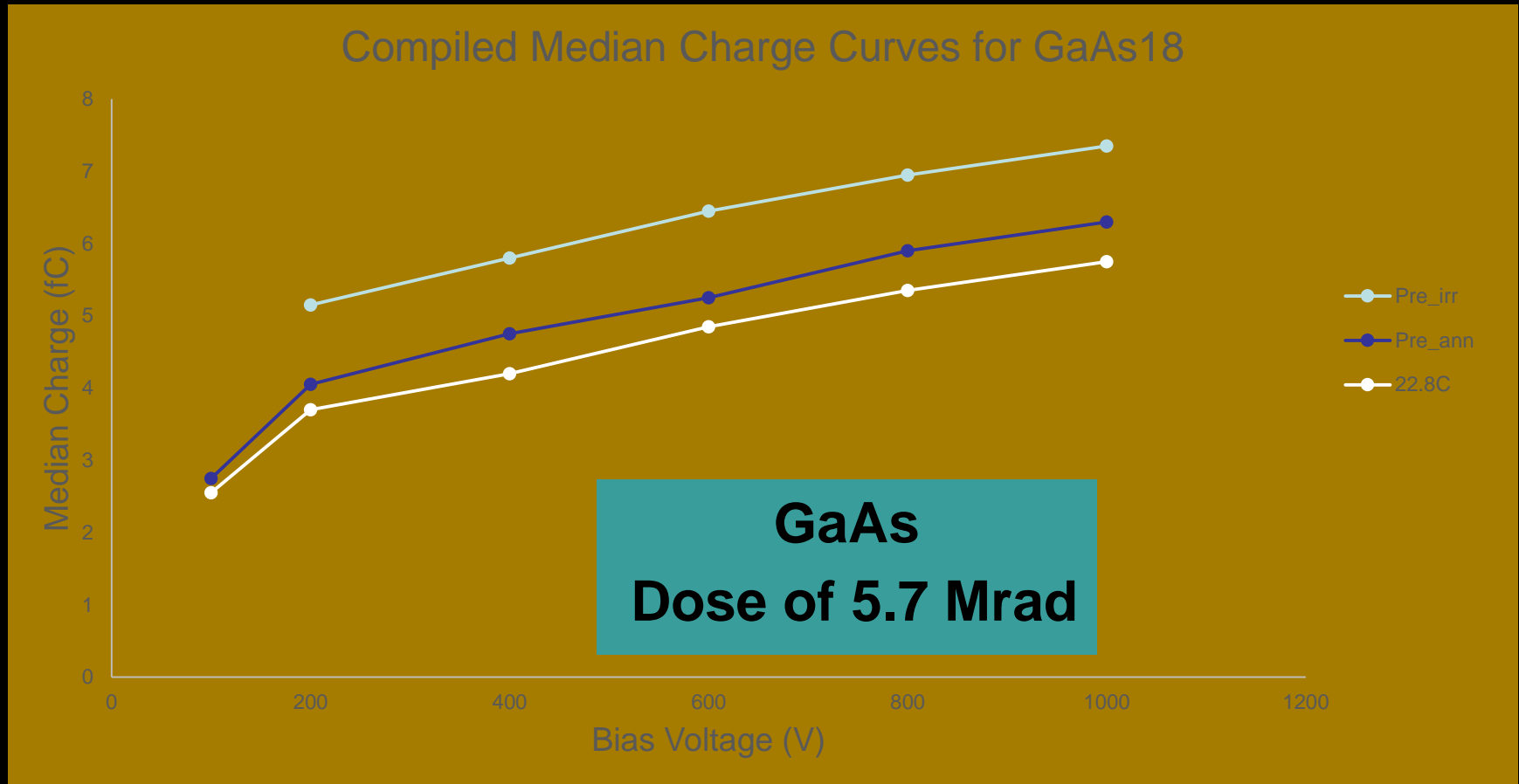
New this past year: (5x5)mm<sup>2</sup> GaAs pad sensors via Georgy Shelkov, JINR Dubna



Irradiated with 5.7 and 21.0 Mrad doses of electromagnetically-induced showers

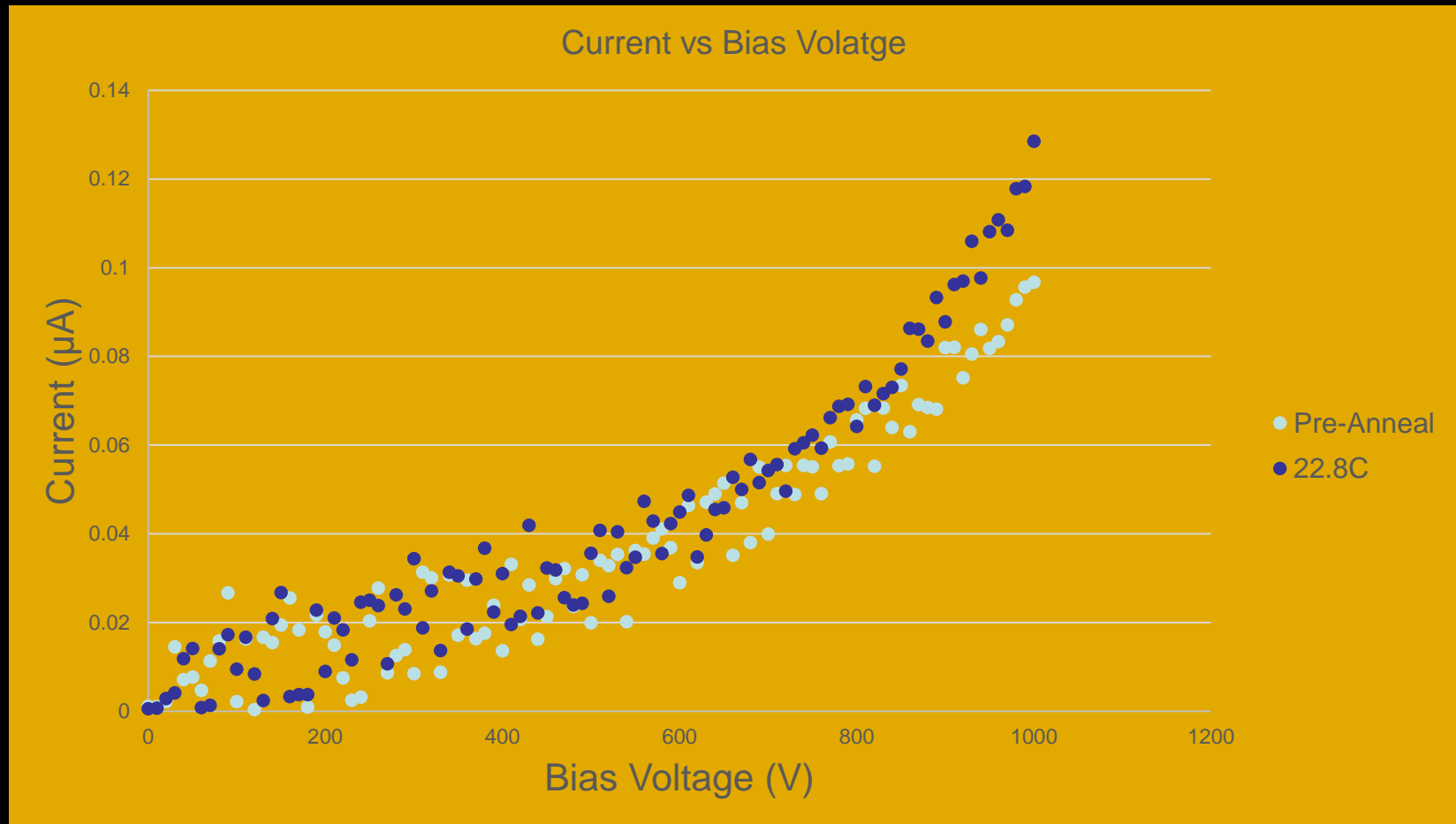
Irradiation temperature 3°C; samples held and measured at -15°C

# GaAs Charge Collection: 5.7 Mrad Exposure



- **15-20% charge loss at 300 ns shaping**
- **Seems to worsen with annealing**
- **Sensor detached at 30° annealing step**

# GaAs Dark Current ( $-10^0$ C)



- **$O(100 \text{ nA/cm}^2)$  after 6 MRad irradiation**
- **Not observed to improve with annealing**

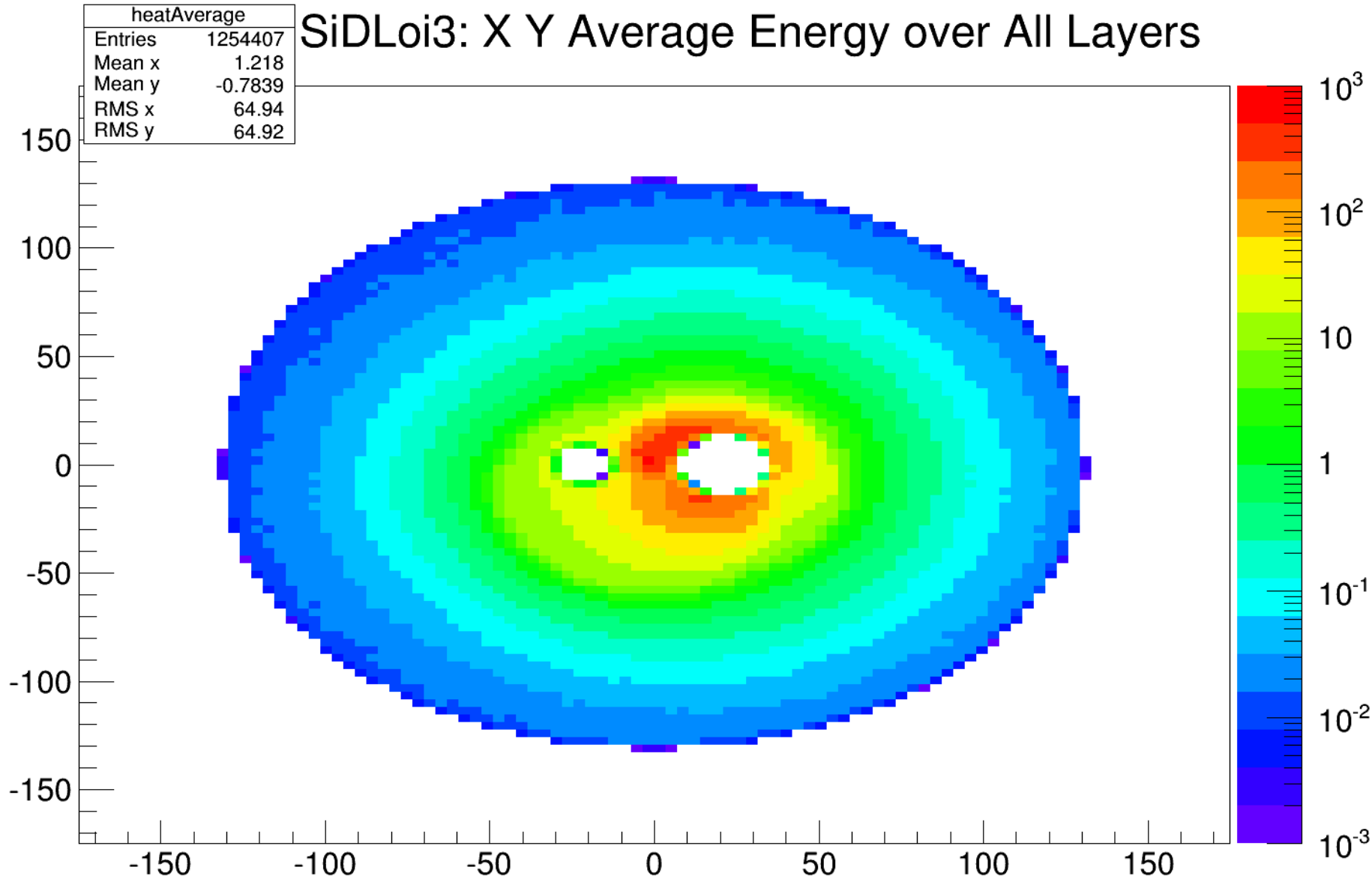


# **Radiation Damage Plans/Opportunities**

- **Silicon sensor studies to high dose, careful monitoring/control of currents, annealing**
- **Further sensor types (GaAs, Sapphire, SiC)**
- **Instrumentation support (FPGA, analysis software)**
- **Silicon sensor for prototype FCAL (ongoing CERN/DESY testbeam studies)**

# BeamCal Simulation Efforts

# Pairs from Beam-Beam Interaction: ~10 TeV per Crossing



# BeamCal Reconstruction: Basic Idea

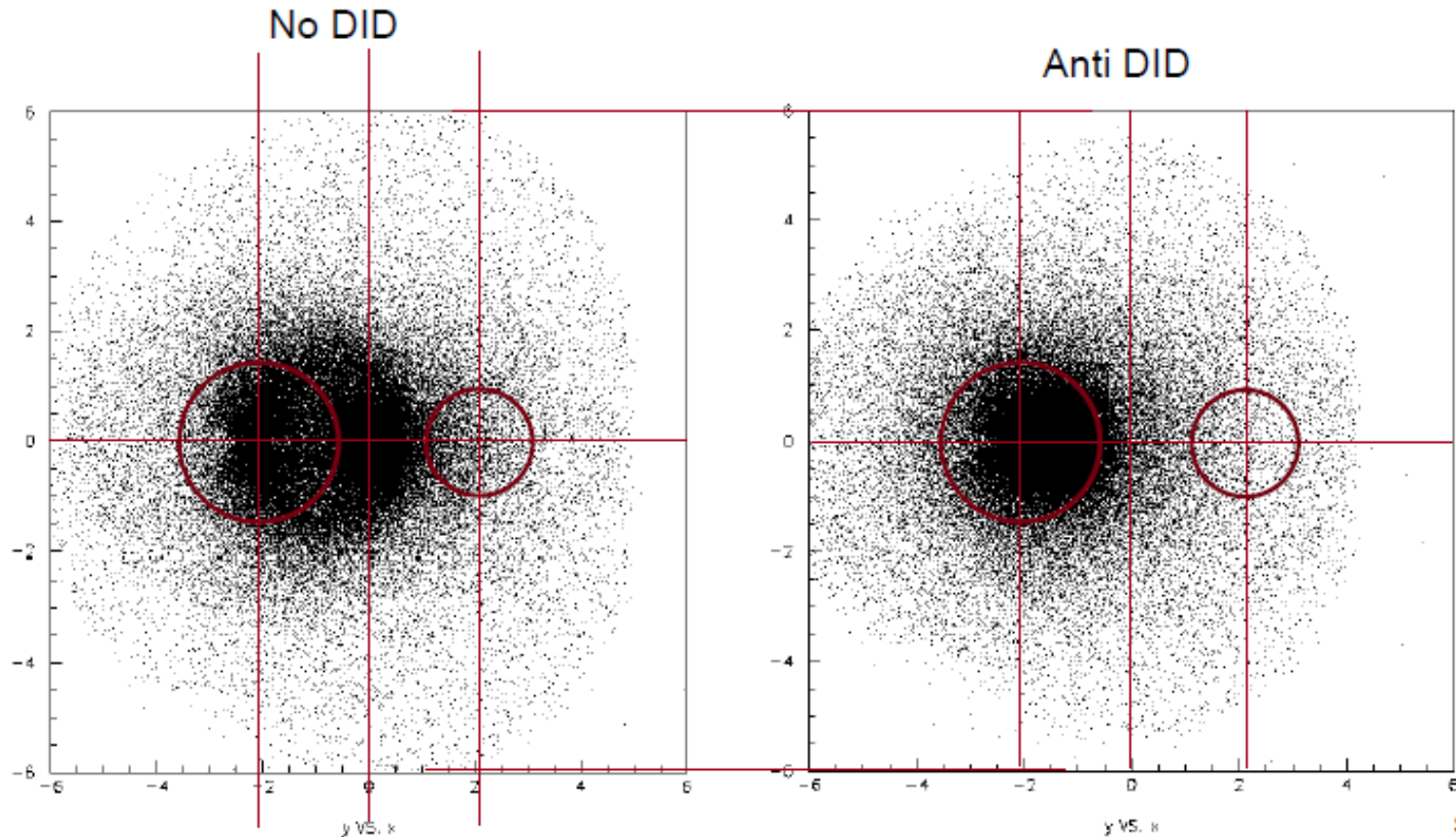
- Find top 50 energy depositions in layer near shower max
- Extend each longitudinally and sum energy in layers
- If one is some number of sigma ( $\sigma_{\text{cut}}$ ) above mean background, accept as signal
- $\sigma_{\text{cut}}$  is single number ( $r, \phi$ -independent) chosen to select 10% of events for which there is nothing but pair background

# Sample Study: Value of AntiDiD

SBWO2\_pairs0001.dat (2009 IP w/o TF)  
Track Hits to 3.0m in 2005 field map

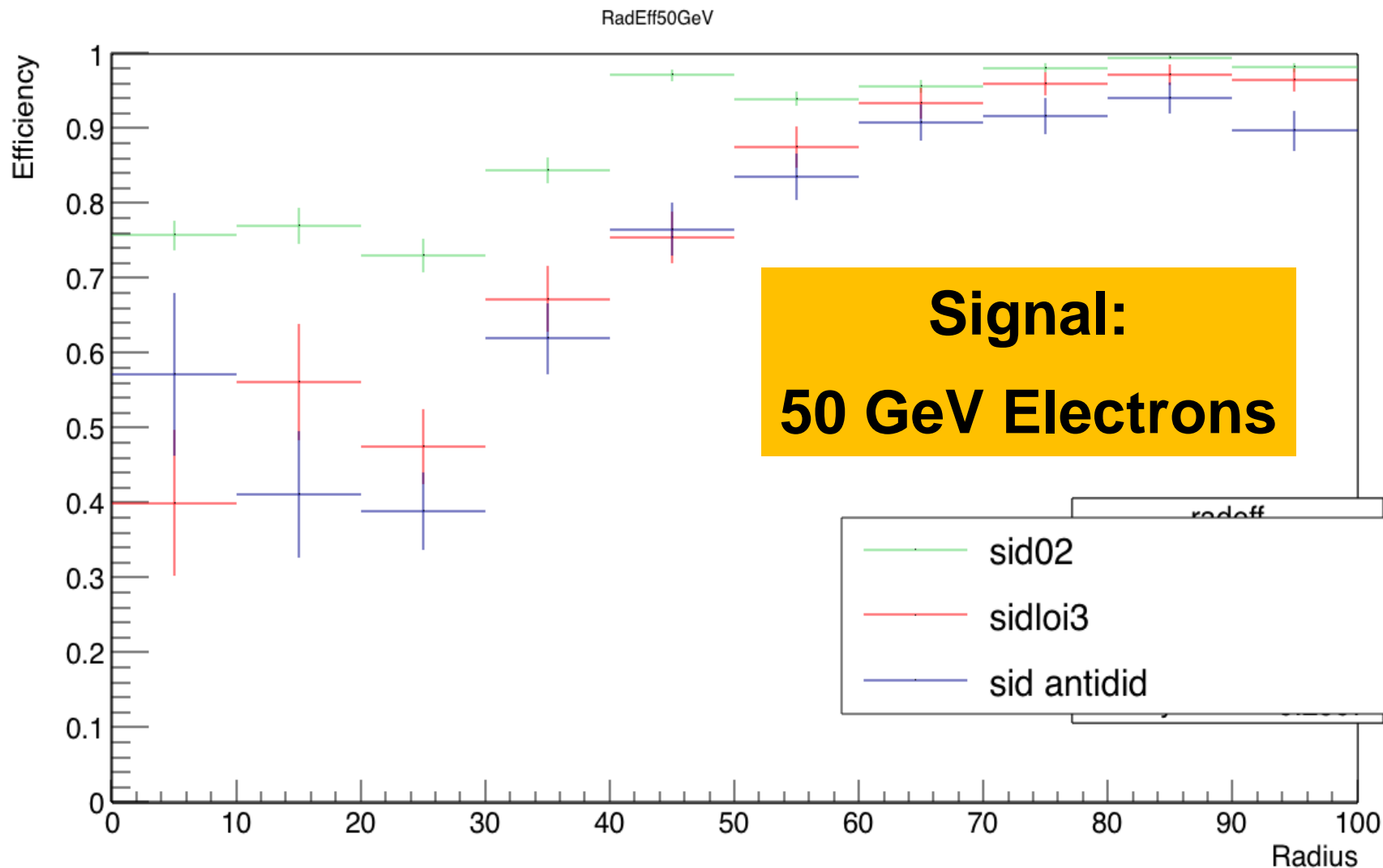
N.B.: “No DID” really means “No Anti DID”

$300\text{cm} \times 0.007 = 2.1\text{cm}$



Tom Markiewicz, SLAC

# Preliminary Results: With and Without AntiDID; also, comparison with DBD (SiD02)



# BeamCal Simulation Cornucopia

Many studies underway/planned/need planning

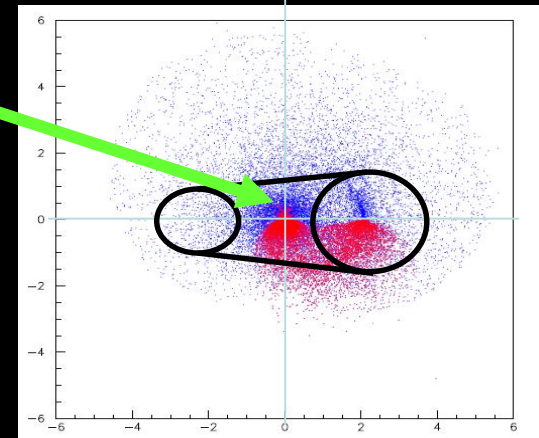
## Instrumentation

- AntiDID of any use?
- “Plug region” between two holes needed? If not, what is optimal geometry?
- Efficiency vs.  $L^*$  (common SiD/ILD  $L^*$ ?)
- Further optimization of reconstruction

## Physics:

- Rejection of two-photon backgrounds to
  - Nearly-degenerate SUSY
  - $H\nu\nu$
- Rejection of (radiative) Bhabha

Etc...



# SiD BeamCal “Opportunities”

Many areas of ongoing work that offer opportunities for increased effort and collaboration

- BEAN chip development (contact Angel Abusleme)
  - T506
  - Simulations
  - Or: whatever you see as relevant and of interest
- Talk to us
- Attend next FCAL collaboration meeting
- DESY Zeuthen 20-21 October

If this machine moves forward, we are going to need to really focus seriously on design.



**Backup**

# MDI Q1 cont'd: Anti-DiD needed?

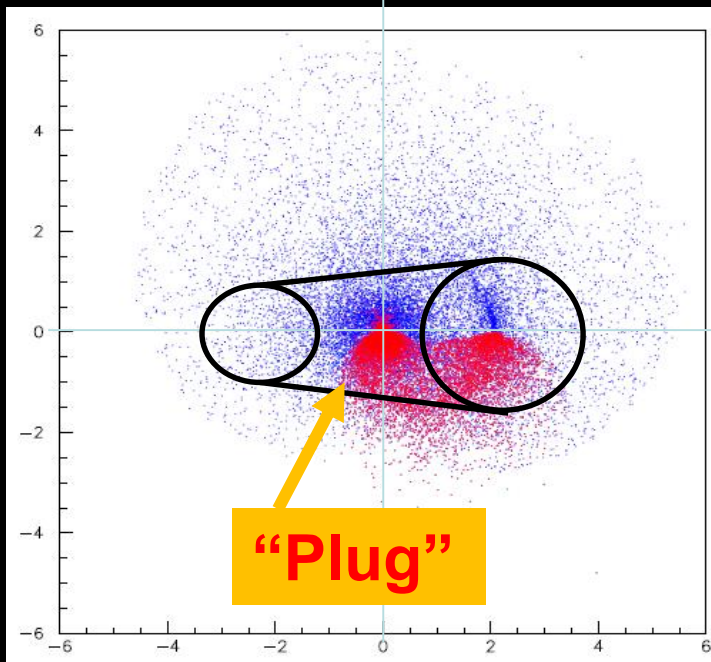
	No DID		AntiDID	
	# Hits	Energy	#Hits	Energy
Out 3cm exit	17.9%	78.4%	81.9%	85.4%
Out 2cm entrance	1.8%	0.4%	0.6%	0.3%
Hit the plug	74.9%	15.2%	6.7%	2.8%
Outside the plug	5.4%	6.0%	10.9%	11.4%

**Tom Markiewicz, SLAC**

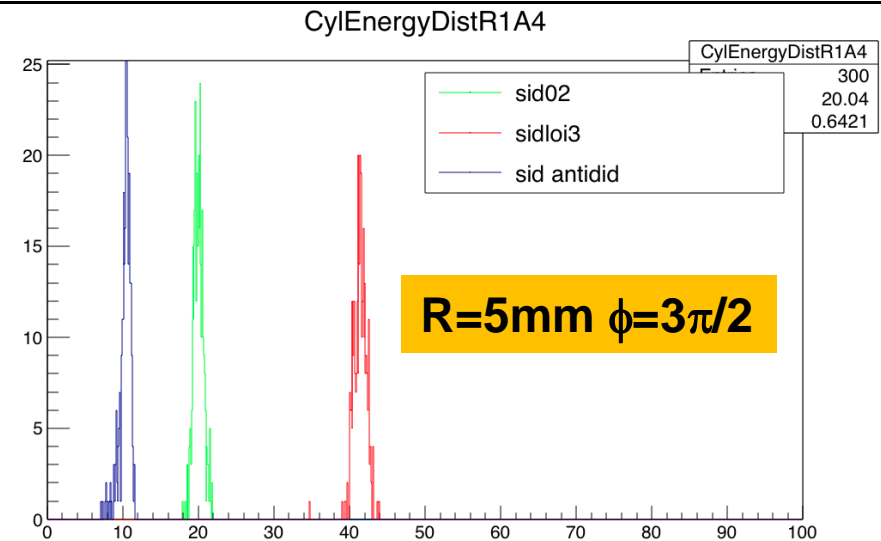
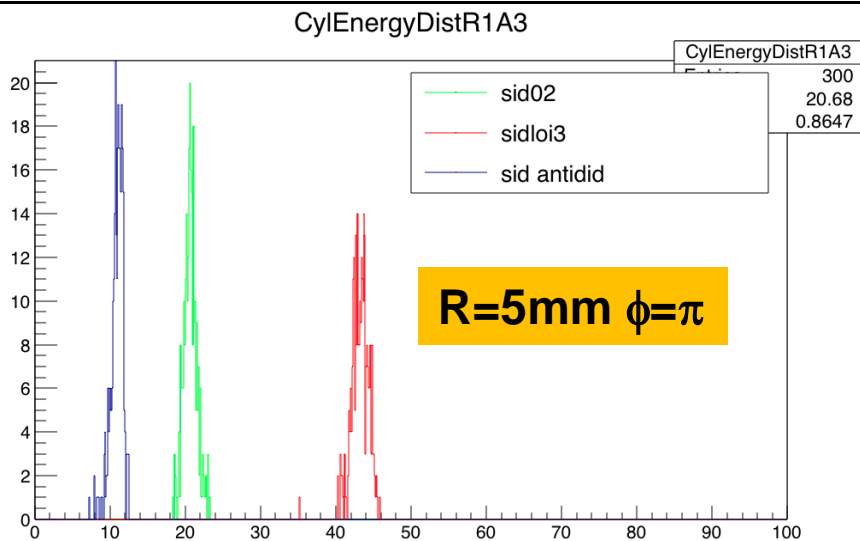
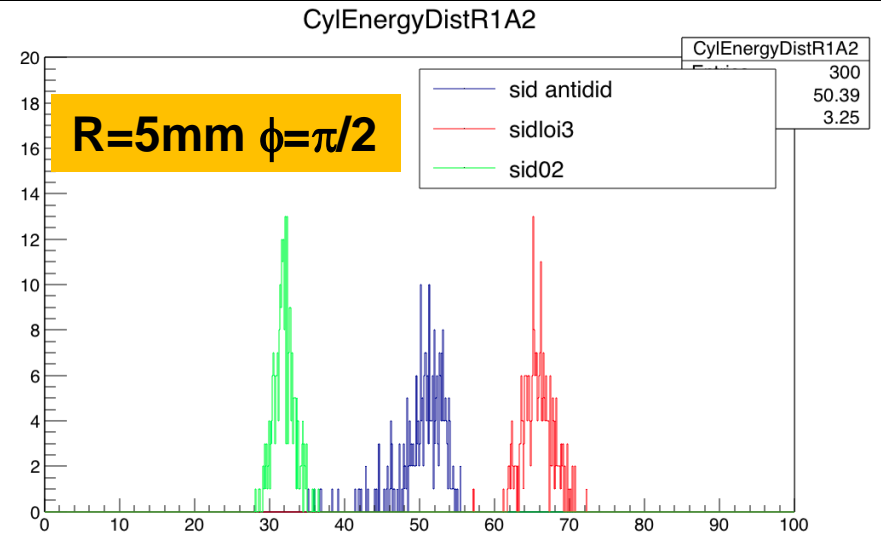
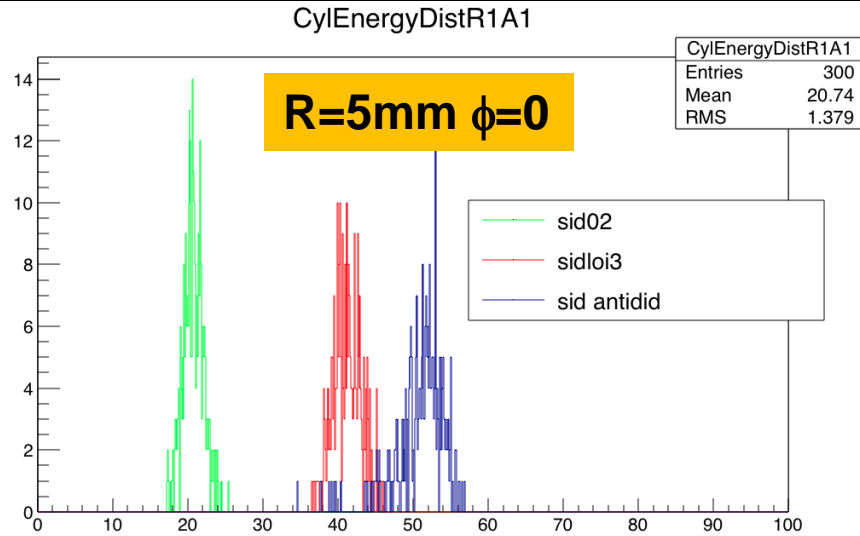
Conclusion:

- The Anti-DID really only helps in the plug region between the beam pipes
- Without the plug to create secondaries, VXD backgrounds should be LESS with no Anti-DID and radiation dose to BEAMCAL should be less

➔ What about the physics?



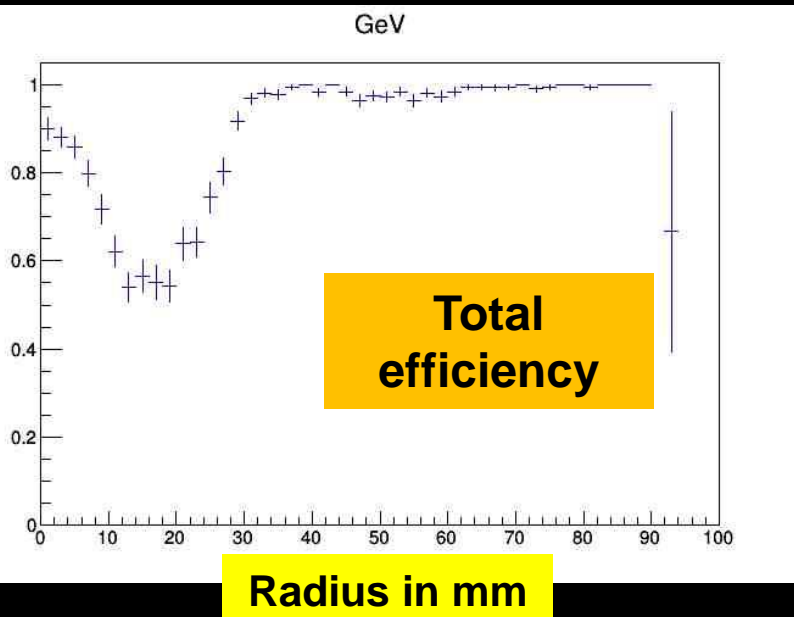
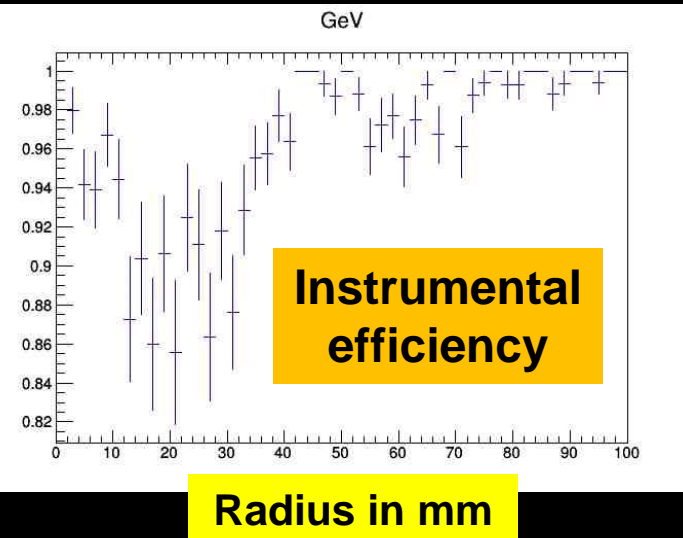
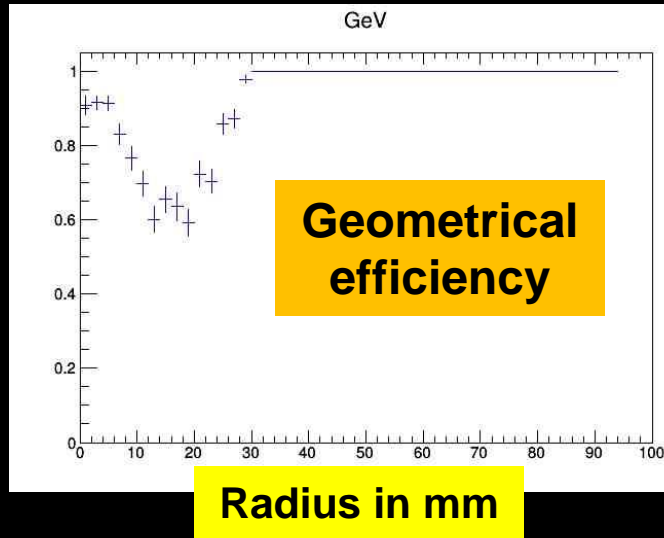
# Energy deposition (summed longitudinally) for various low-radius points on BeamCal



# MDI Q2: BeamCal Location and Geometry

- First step: Need to (re)-learn how to simulate the SLD IP and BeamCal environment → underway
- Need to center BeamCal on exit hole (correct?)
- Factorize BeamCal efficiency estimates: total efficiency a product of
  - Geometrical efficiency (did the electron hit the instrumented region?)
  - Instrumental efficiency (if so, was an electron reconstructed?)

# Factorized efficiency vs radius results for 100 GeV electrons



- What happens if “plug” is removed (VXD and BeamCal backgrounds)?
- What is effect on SUSY sensitivity in degenerate scenarios?

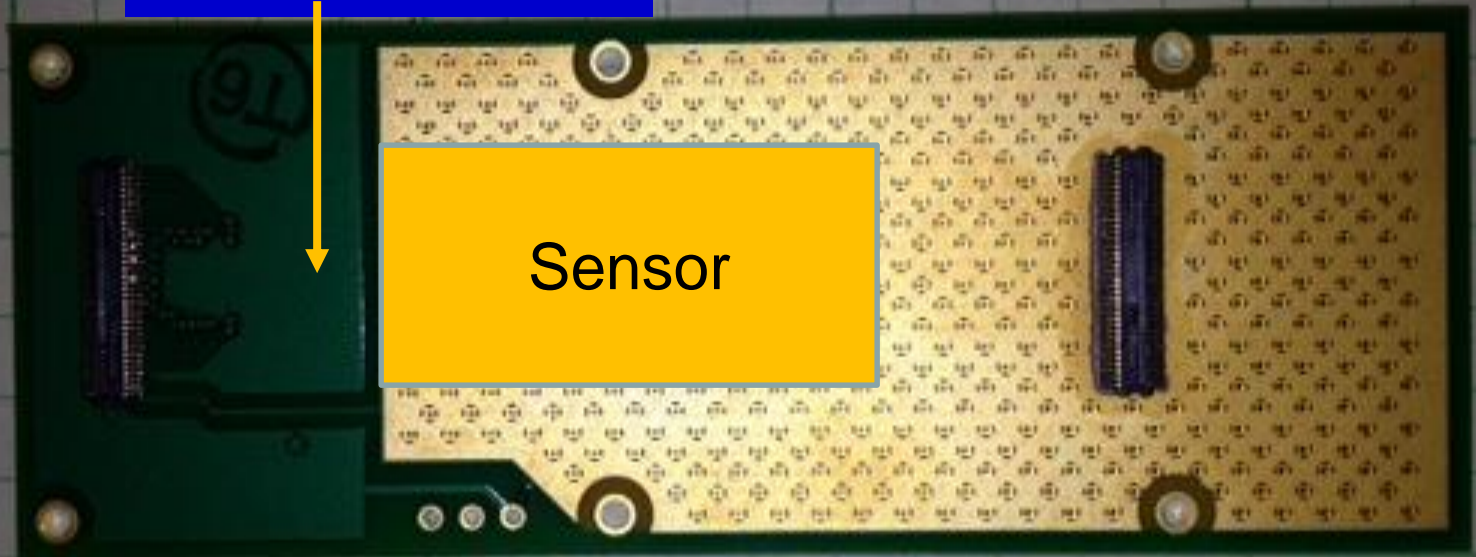
# Hadronic Processes in EM Showers

There seem to be three main processes for generating hadrons in EM showers (all induced by **photons**):

- Nuclear (“giant dipole”) resonances  
Resonance at 10-20 MeV ( $\sim E_{\text{critical}}$ )
  - Photoproduction  
Threshold seems to be about 200 MeV
  - Nuclear Compton scattering  
Threshold at about 10 MeV;  $\Delta$  resonance at 340 MeV
- These are largely isotropic; must have most of hadronic component develop near sample

# Daughter Board Assembly

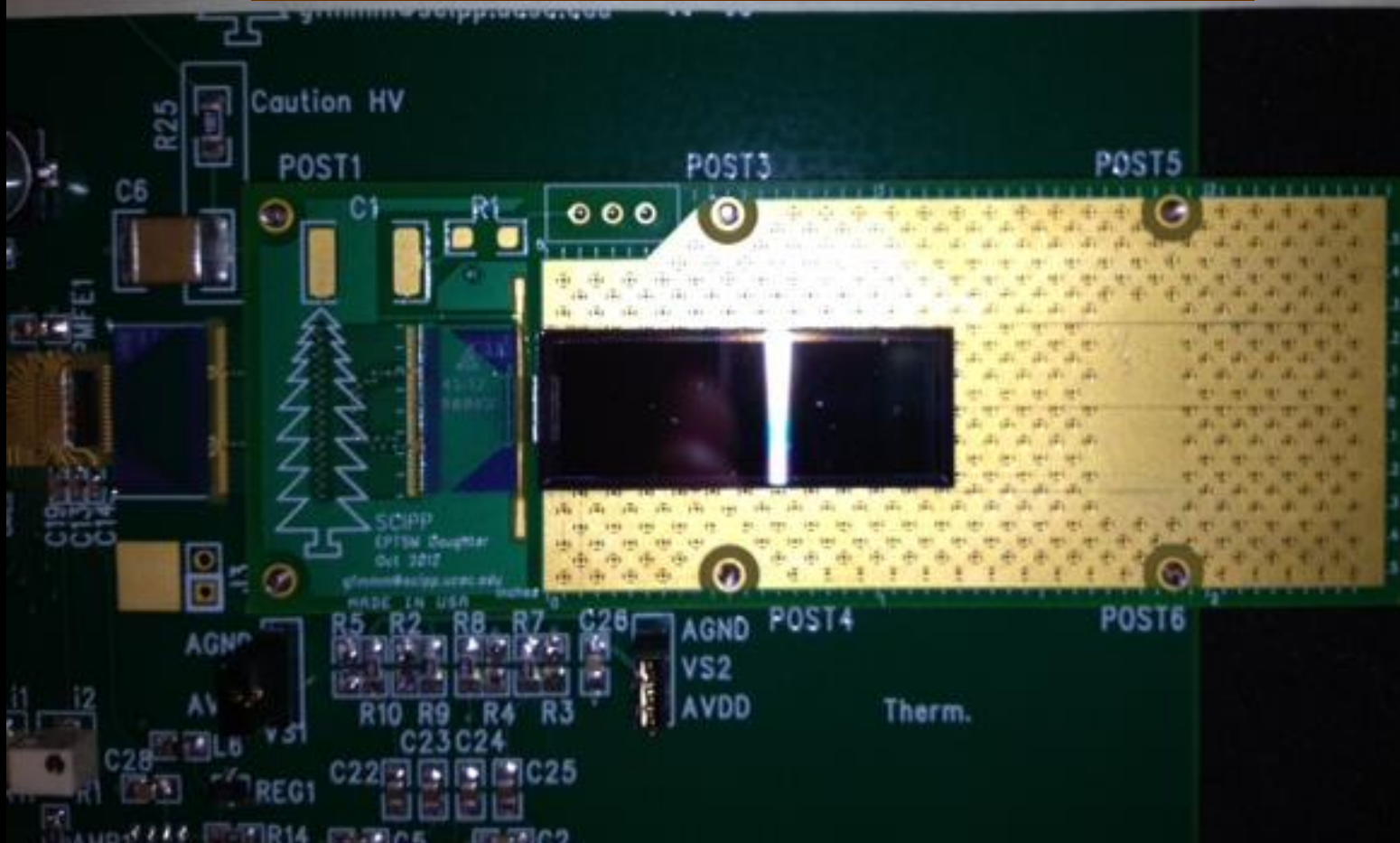
Pitch adapter,  
bonds



Sensor

1 inch

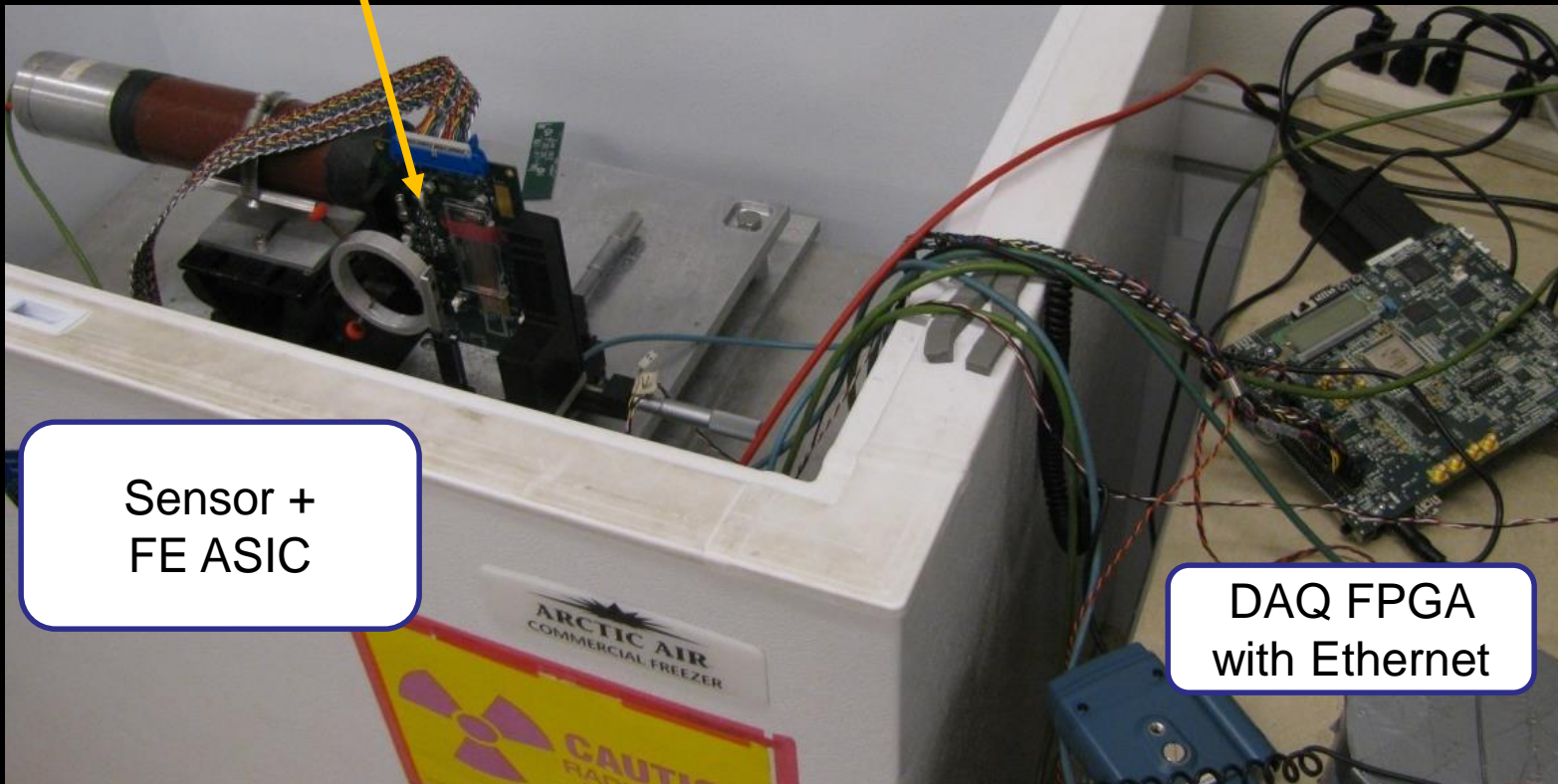
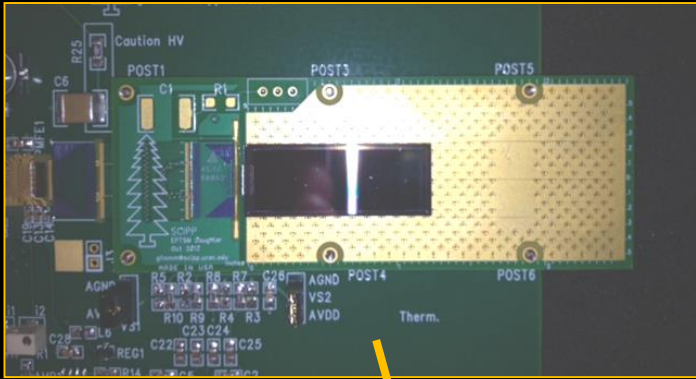
# Daughter/Readout Board Assembly





# Charge Collection Apparatus

- Readout: 300 ns



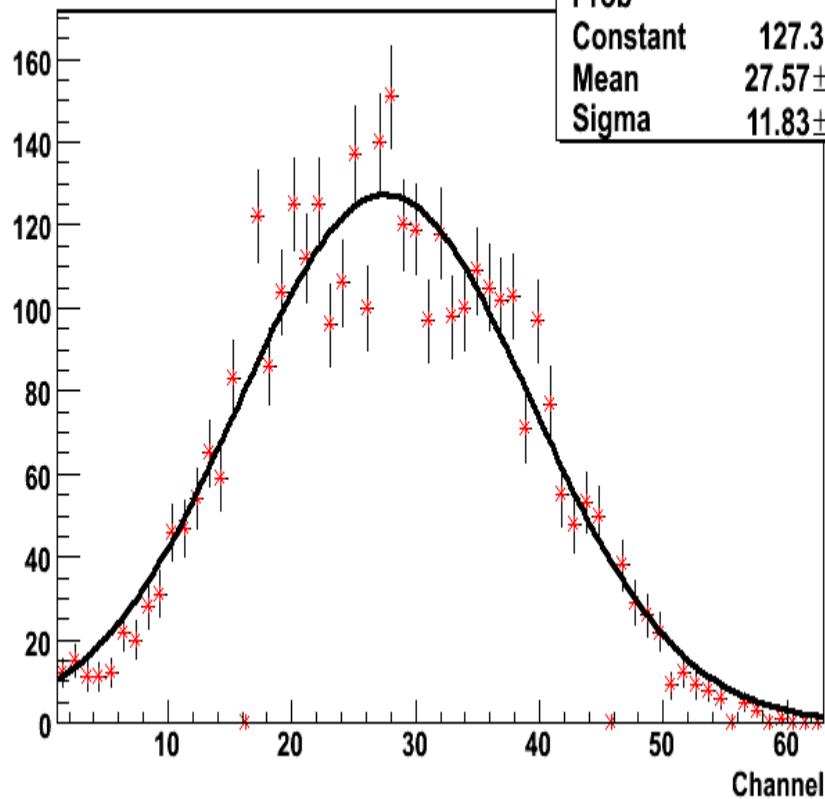
Sensor +  
FE ASIC

DAQ FPGA  
with Ethernet

# Charge Collection Measurement

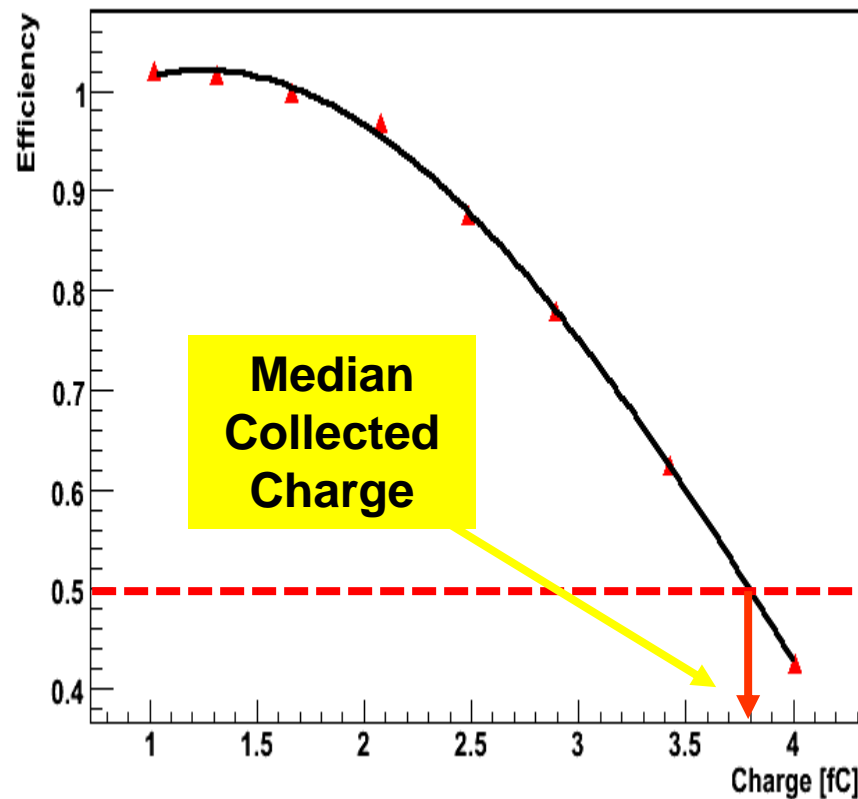
## 2.3 MeV e<sup>-</sup> through sensor into scintillator

Coincidence Profile



$\chi^2 / \text{ndf}$	7240 / 53
Prob	0
Constant	$127.3 \pm 0.3$
Mean	$27.57 \pm 0.03$
Sigma	$11.83 \pm 0.03$

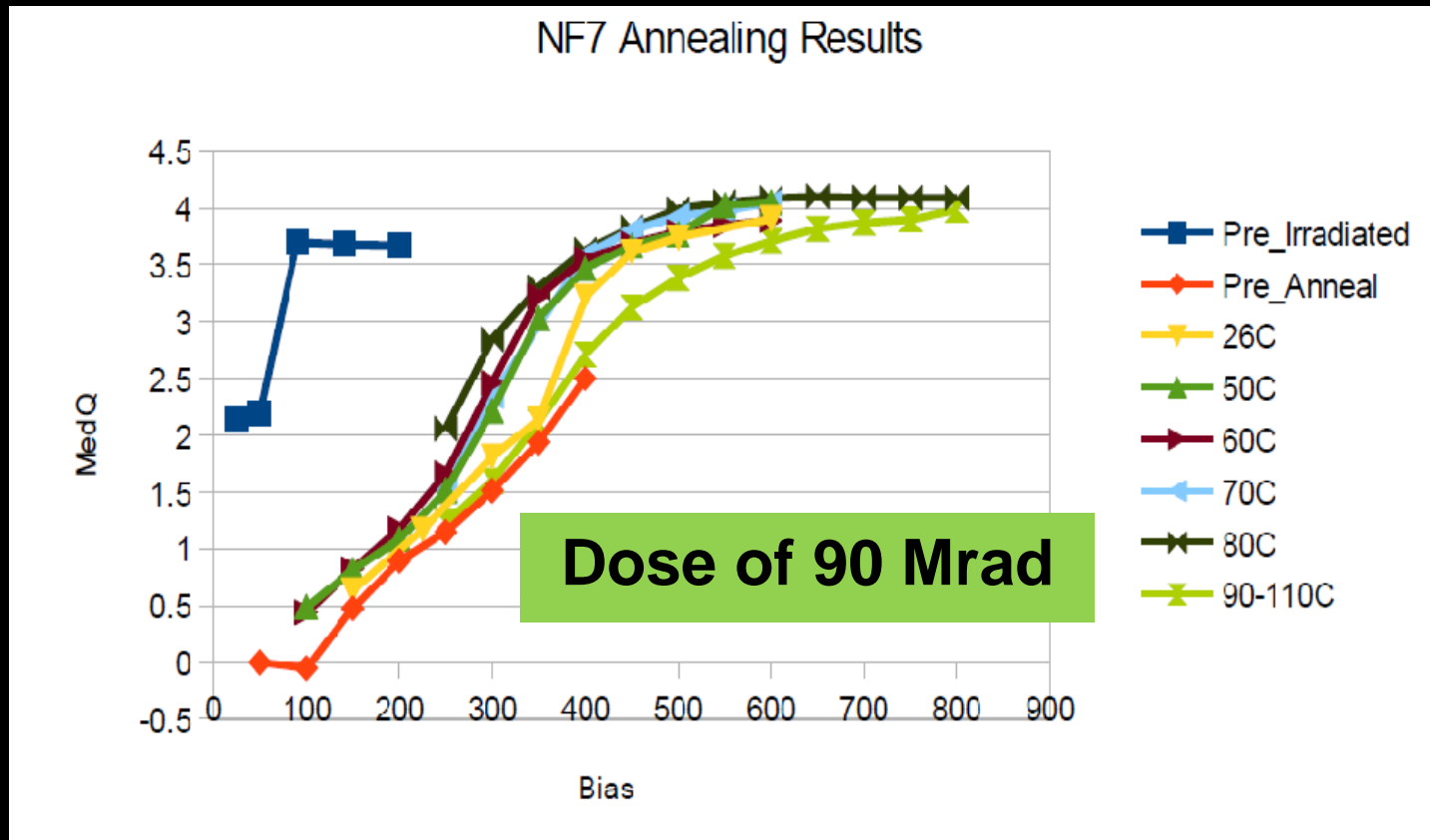
Charge Collection Efficiency vs. Threshold : Bias = 200 [V]



Channel-over-threshold profile

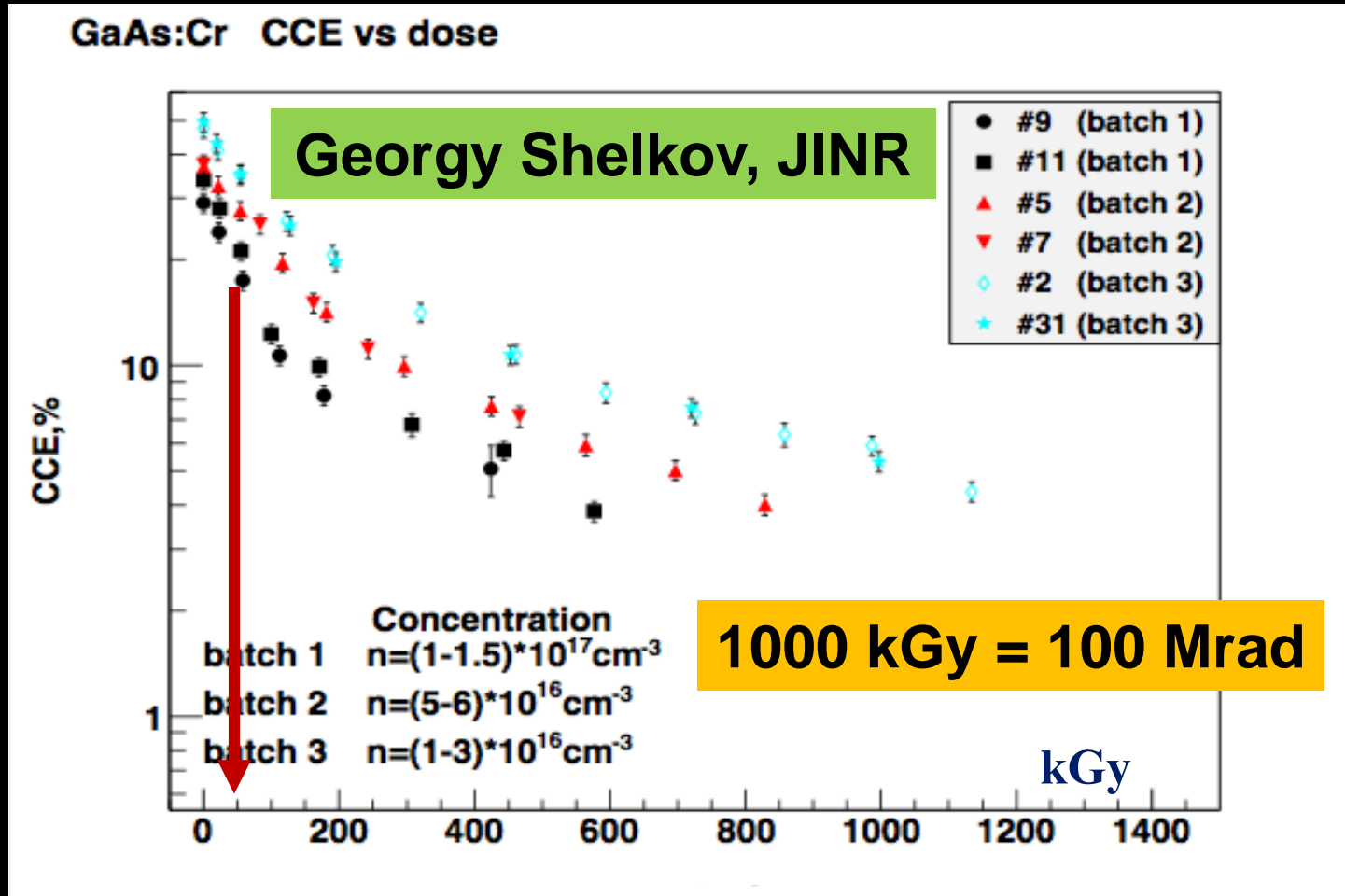
Efficiency vs. threshold

# Results: NF Sensor to 90 Mrad, Plus Annealing Study



**Limited beneficial annealing to 90°C  
(reverse annealing above 100°C?)**

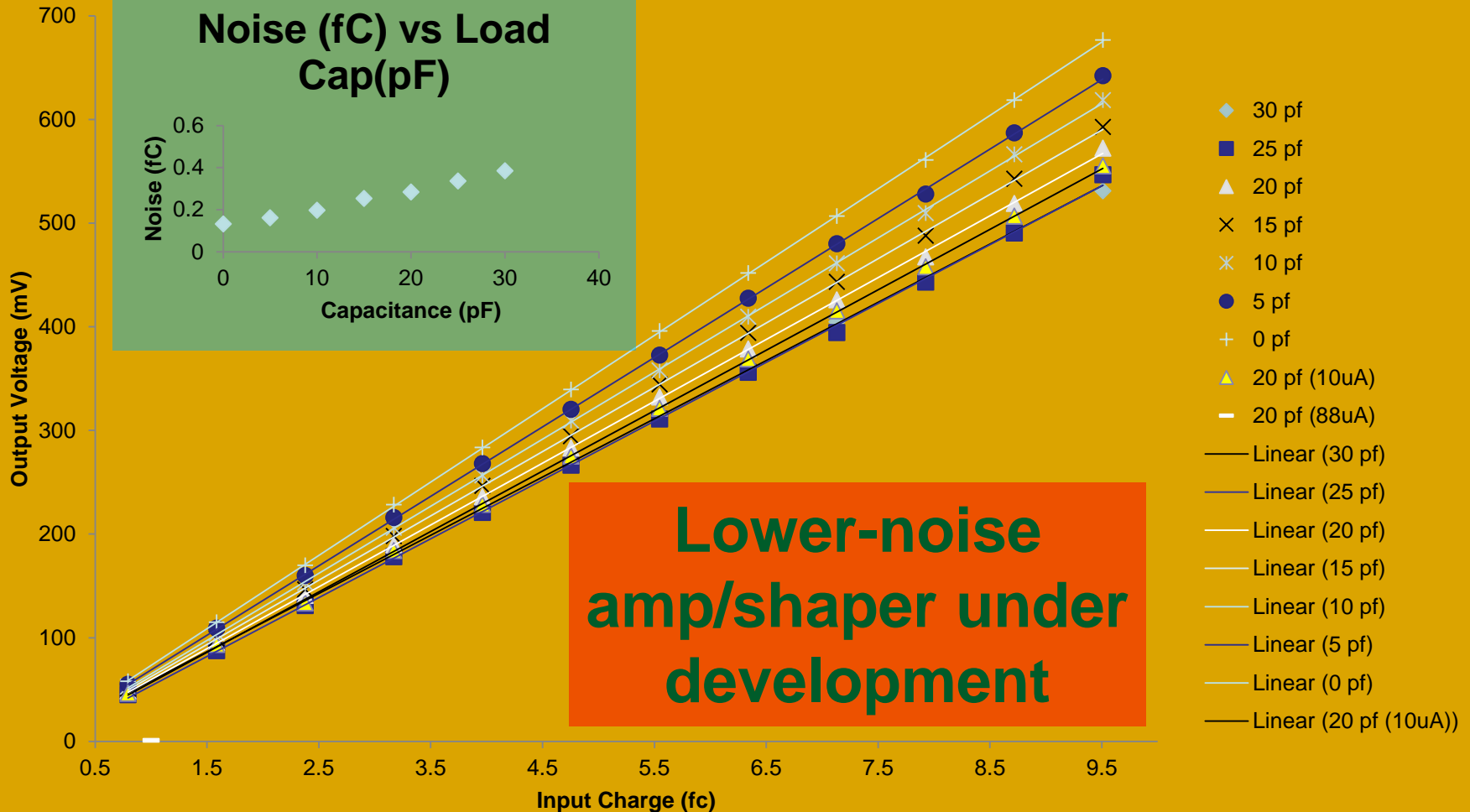
# Compare to Direct Electron Radiation Results (no EM Shower)



Roughly consistent with direct result

# Single-Channel Readout

Output Voltage (mV) vs Input charge (fc)



**Needed for high-dose GaAs, and SiC (0.25 fC signal) and Sapphire (0.09 fC signal)**

# Plans for T506

**Have been promised beam time this spring/summer**

**Hoping for high intensity running; SLAC has not yet announced plans and offered running slots**

**Continue Si irradiation studies to high fluence**

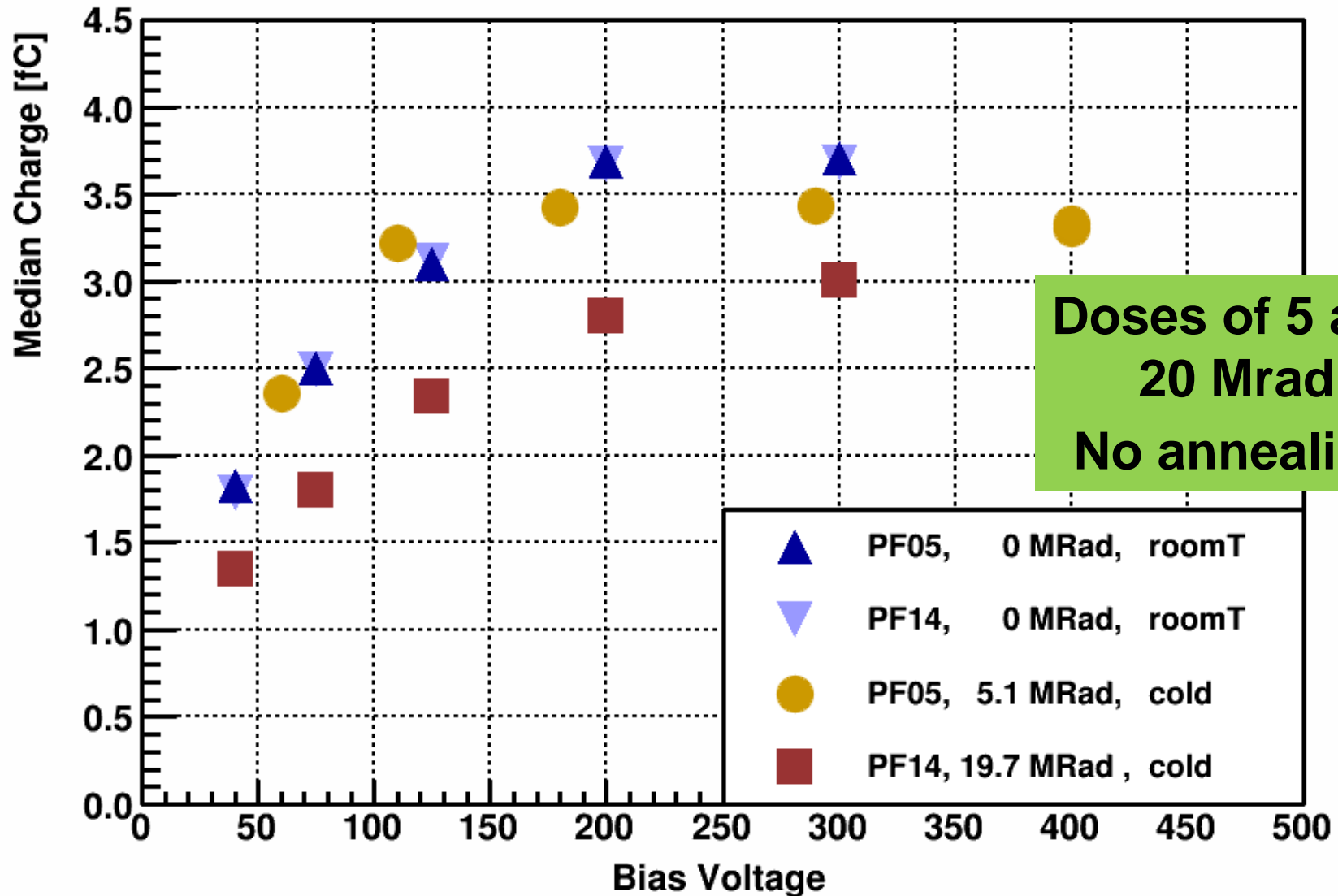
- **Careful annealing studies**
- **Studies leakage currents as well as charge collection**

**Single-channel readout for novel sensors**

- **Assess 20 Mrad GaAs sample**
- **Sapphire irradiation (levels?)**
- **Silicon Carbide (levels?)**

# Results: PF sensors

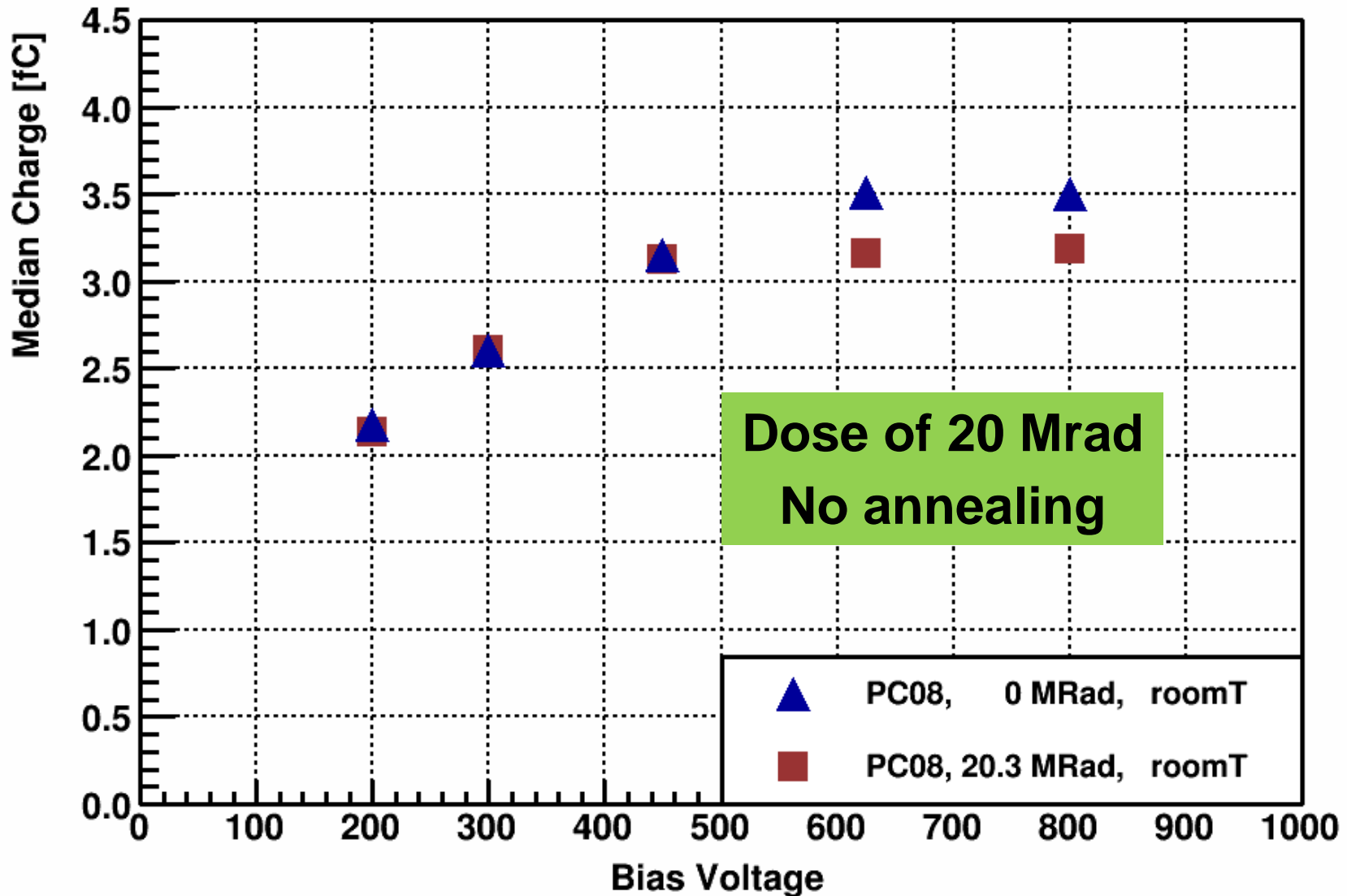
Median Charge vs Bias Voltage, P-type Float Zone sensors



Doses of 5 and 20 Mrad  
No annealing

# Results: PC sensors

Median Charge vs Bias Voltage, P-type Magnetic Czochralski sensors





# Results: NF sensor for low dose

